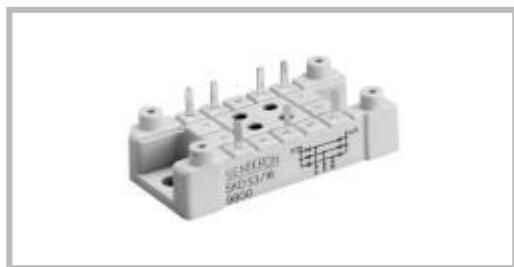


SKD 83



V_{RSM} V	V_{RRM}, V_{DRM} V	I_c
500	400	SKI
900	800	SKI
1300	1200	SKI
1600	1400	SKI
1700	1600	SKI
1900	1800	SKI

Power Bridge Rectifiers

SKD 83

Features

- Glass passivated silicon chips
- Low thermal impedance through use of direct copper bonded aluminum substrate (DCB) base plate
- Blocking voltage up to 1800 V
- Suitable for PCB mounting and wave soldering
- For applications with high vibrations we recommend to fasten the bridge to the pcb with 4 selftapping screw

Typical Applications

- Three phase rectifiers for power supplies
- Input rectifiers for variable frequency drives
- Rectifiers for DC motor field supplies
- Battery charger rectifiers

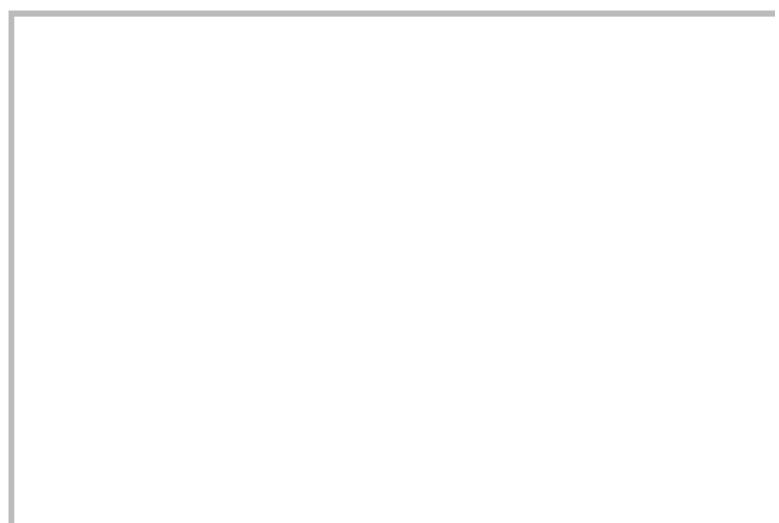
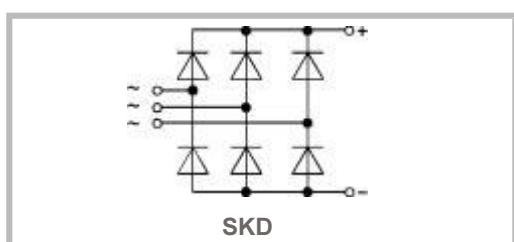
¹⁾ Freely suspended or mounted on an insulator

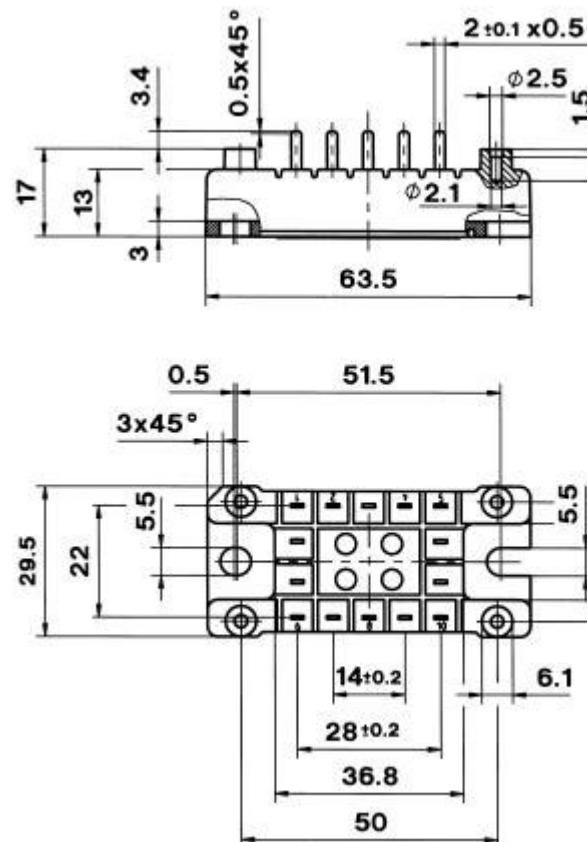
²⁾ Mounted on a painted metal sheet of min. 250 x 250 x 1 mm

³⁾ $T_{solder} = 250 \pm 10^\circ\text{C}$ (10 s)

I_D	Conditions $T_s = 95^\circ\text{C}$ $T_a = 45^\circ\text{C}$; isolated ¹⁾ $T_a = 45^\circ\text{C}$; chassis ²⁾ $T_a = 45^\circ\text{C}$; P5A/100 (R4A/120) $T_a = 35^\circ\text{C}$; P1A/120F
I_{FSM}	$T_{vj} = 25^\circ\text{C}; 10\text{ ms}$ $T_{vj} = 150^\circ\text{C}; 10\text{ ms}$
i^{2t}	$T_{vj} = 25^\circ\text{C}; 8,3 \dots 10\text{ ms}$ $T_{vj} = 150^\circ\text{C}; 8,3 \dots 10\text{ ms}$
V_F $V_{(TO)}$ r_T I_{RD}	$T_{vj} = 25^\circ\text{C}; I_F = 80\text{ A}$ $T_{vj} = 150^\circ\text{C}$ $T_{vj} = 150^\circ\text{C}$ $T_{vj} = 25^\circ\text{C}; V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$ $T_{vj} = 150^\circ\text{C}; V_{RD} = V_{RRM}$
$R_{th(j-s)}$ $R_{th(j-a)}$ T_{vj} T_{stg}	per diode total isolated ¹⁾ chassis ²⁾
V_{isol} M_s M_t a m	a. c. 50 Hz; r.m.s.; 1 s / 1 min. to heatsink; SI units
Case	

Cases / Circuits





Case G 55

Diagrams

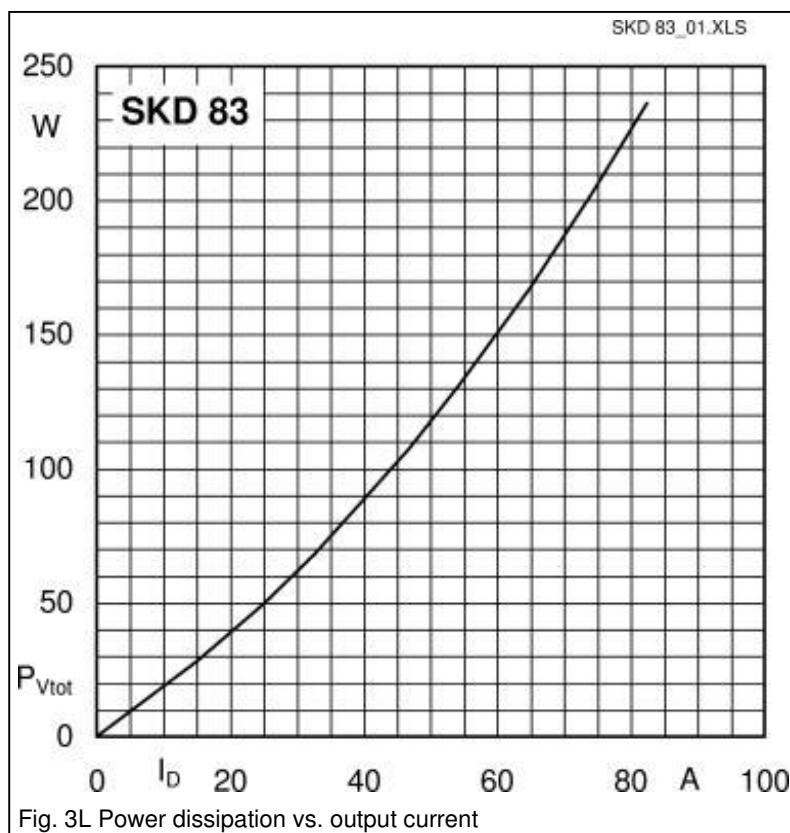


Fig. 3L Power dissipation vs. output current

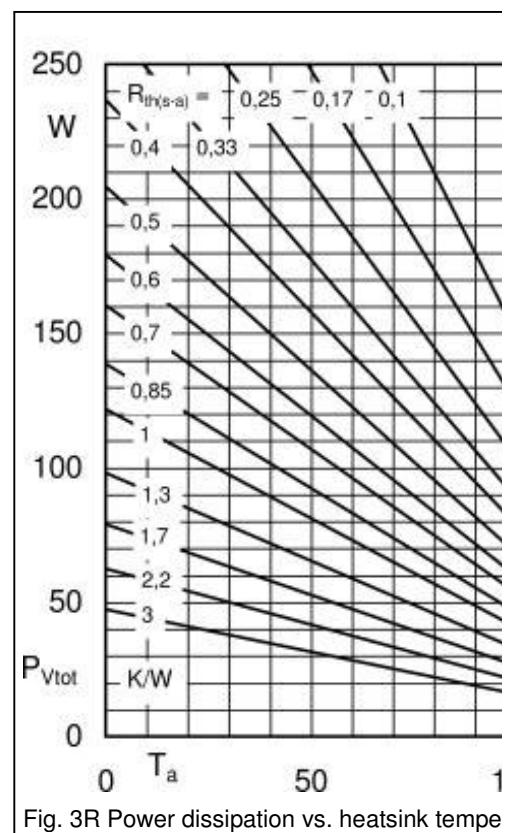


Fig. 3R Power dissipation vs. heatsink tempe